

022704

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of: Paul A. Farrar

Title: INTEGRATED CIRCUIT AND SEED LAYERS

Attorney Docket No.: 303.673US3

Customer No.: 21186

PATENT APPLICATION TRANSMITTAL**MAIL STOP PATENT APPLICATION**

Commissioner for Patents

P.O. Box 1450

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We are transmitting herewith the following attached items and information (as indicated with an "X"):

Return postcard.

DIVISIONAL of prior Patent Application No.(10/117041) (under 37 CFR 1.53(b)) comprising:

Specification (59 pgs, including claims numbered 1 through 79 and a 1 page Abstract).

Formal Drawing(s) (47 sheets).

Copy of signed Declaration (3 pgs) from prior application.

Copy of Power of Attorney from prior application (1 pgs).

Incorporation by Reference: *The entire disclosure of the prior application, from which a copy of the oath or declaration is supplied herewith, is considered as being part of the disclosure of the accompanying application and is hereby incorporated by reference therein.*

Check in the amount of \$2692.00 to pay the filing fee.

Prior application is assigned of record to Micron Technology, Inc.

Information Disclosure Statement (2 pgs), Form 1449 (10 pgs)

References NOT enclosed, cited in prior application.

A Communication Concerning Related Applications (2 pgs.).

The filing fee has been calculated below as follows:

	No. Filed	No. Extra	Rate	Fee
TOTAL CLAIMS	79-20	59	x 18.00 =	\$1062.00
INDEPENDENT CLAIMS	13-3	10	x 86.00 =	\$860.00
[] MULTIPLE DEPENDENT CLAIMS PRESENTED				\$0.00
BASIC FEE				\$770.00
TOTAL				\$2692.00

Please charge any additional required fees or credit overpayment to Deposit Account No. 19-0743.

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.

Customer Number: 21186

By: David R. Cochran
Atty: David R. Cochran
Reg. No. 46,632"Express Mail" mailing label number: EV415950039USDate of Deposit: February 27, 2004

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17548 U.S. PTO
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022704

S/N Unknown

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Paul A. Farrar

Examiner: Unknown

Serial No.: Unknown

Group Art Unit: Unknown

Filed: Herewith

Docket: 303.673US3

Title: INTEGRATED CIRCUIT AND SEED LAYERS

COMMUNICATION CONCERNING RELATED APPLICATION(S)

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Applicant would like to bring to the Examiner's attention the following related application(s) in the above-identified patent application:

<u>Serial/Patent No.</u>	<u>Filing Date</u>	<u>Attorney Docket</u>	<u>Title</u>
09/488098 6429120	January 18, 2000	303.618US1	METHOD AND APPARATUS FOR MAKING INTEGRATED-CIRCUIT WIRING FROM COPPER, SILVER, GOLD, AND OTHER METALS
09/484303	January 18, 2000	303.648US1	METHODS FOR MAKING INTEGRATED-CIRCUIT WIRING FROM COPPER, SILVER, GOLD, AND OTHER METALS
09/483869 6420262	January 18, 2000	303.664US1	STRUCTURES AND METHODS TO ENHANCE COPPER METALLIZATION
09/483881	January 18, 2000	303.672US1	SELECTIVE ELECTROLESS-PLATED COPPER METALLIZATION
10/196078	July 16, 2002	303.664US2	STRUCTURES AND METHODS TO ENHANCE COPPER METALLIZATION
10/196081	July 16, 2002	303.664US3	STRUCTURES AND METHODS TO ENHANCE COPPER METALLIZATION
10/211855	August 1, 2002	303.618US2	METHOD AND APPARATUS FOR MAKING INTEGRATED-CIRCUIT WIRING FROM COPPER, SILVER, GOLD, AND OTHER METALS

10/195965	July 16, 2002	303.664US4	STRUCTURES AND METHODS TO ENHANCE COPPER METALLIZATION
10/634274	August 5, 2003	1303.110US1	H2 Plasma Treatment
09/534224 6426289	March 24, 2000		
10/137293	May 3, 2002		

Respectfully submitted,

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By Applicant's Representatives,

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